

Oral Presentation

[FLX6]Advanced Process and Evaluation for Flexible Electronics

Chair: Tadahiro Furukawa (Yamagata University)

Co-Chair: Akira Nakazawa (AGC Inc.)

Fri. Nov 29, 2019 3:00 PM - 4:00 PM Room 204 (2F)

3:25 PM - 3:45 PM

[FLX6-2]Analysis and Design of Mechanical Stresses on Foldable Devices

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Keywords:Mechanical stresses, Foldable devices, Endurance test, Mechanoluminescent material

Knowledge of mechanical stresses on foldable devices is important to develop them. When you study stresses, you should control motion profile then study dynamic strain energy. In our study, we slightly adjusted each testing conditions to figure out effect from these difference and sensitivity of the analyzing method.